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PATENT NUMBER and
ISSUE DATE

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APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10002779	10/29/2001	438	496	2818	

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10002779	10/29/2001	438		2818	D. VU

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*PRIORITY CLAIM IS A DIV OF 09/590,795 06/08/2001

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*PRIORITY CLAIMS VERIFIED: None DV

FOR PUBLICATION <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	6047-61466	
Title: Methods for forming and integrated circuit structures containing ruthenium and tungsten containing layers		

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner David Helms Supervisor Technology Center 2800		DRAWING	
Amount Due Date Paid		Sheets Drwg. Figs. Drwg. Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
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